

Form layer of material
on wafer having
thick and thin
regions.

102

Form narrow and wide
regions in the layer of
material that correspond
to thick and thin
regions of the
wafer

104

Figure 1 100

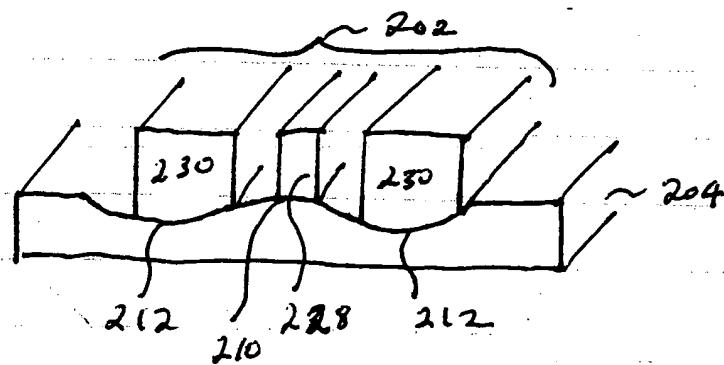
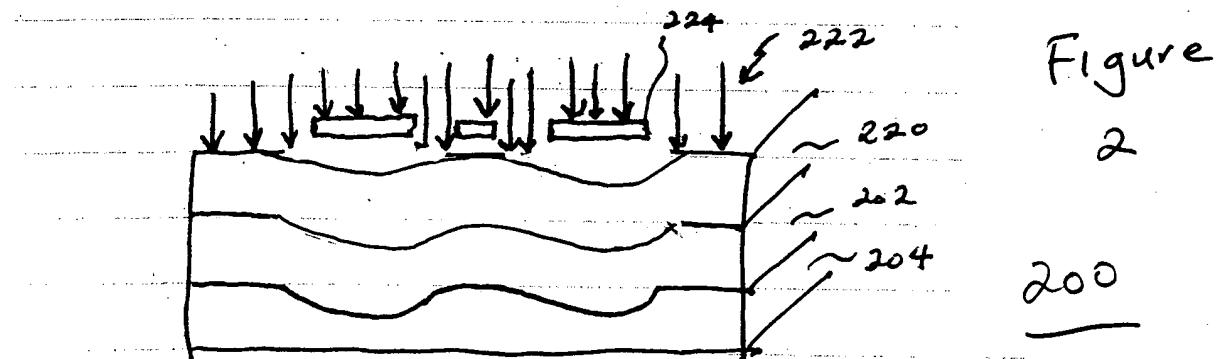
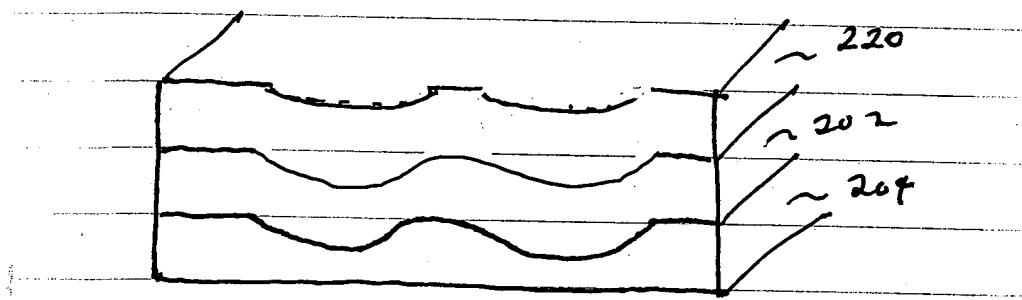
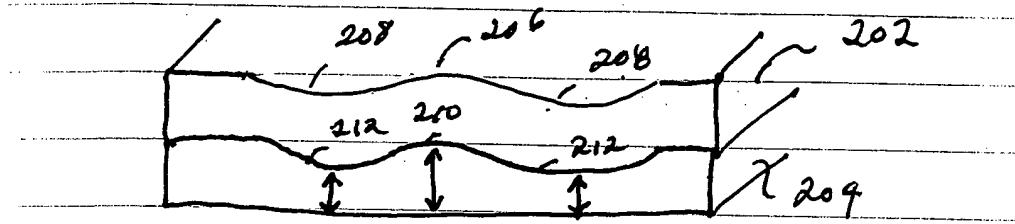


Figure
2

200

Form 1st layer of material
on wafer having thick
and thin regions

300

Form sacrificial layer
of material on 1st
layer of material

304

Form narrow and wide
regions in sacrificial
layer that correspond
to thick and thin
regions

366

Figure 3

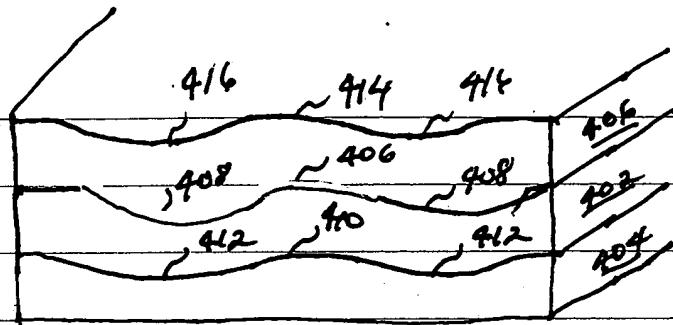


Figure
4

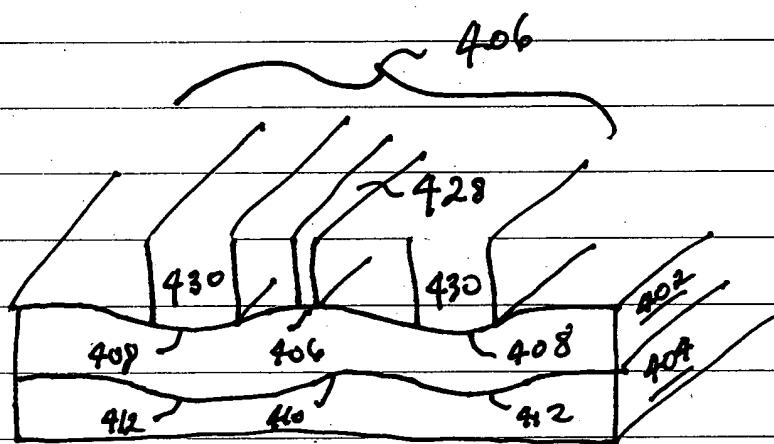
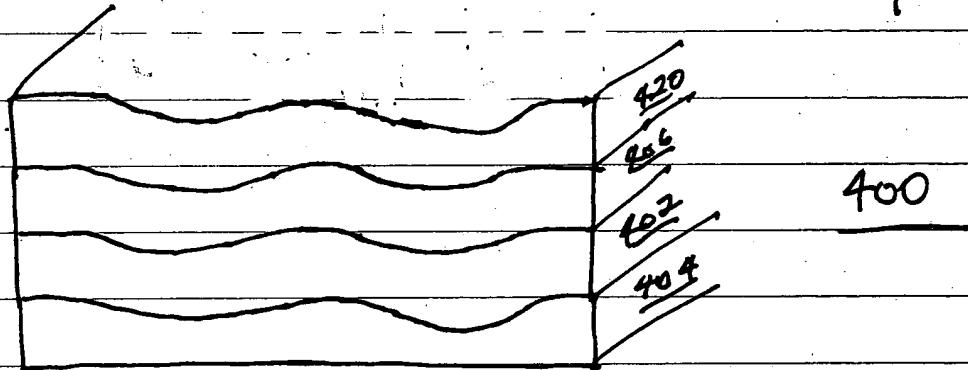


Figure 5

